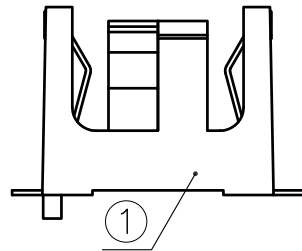
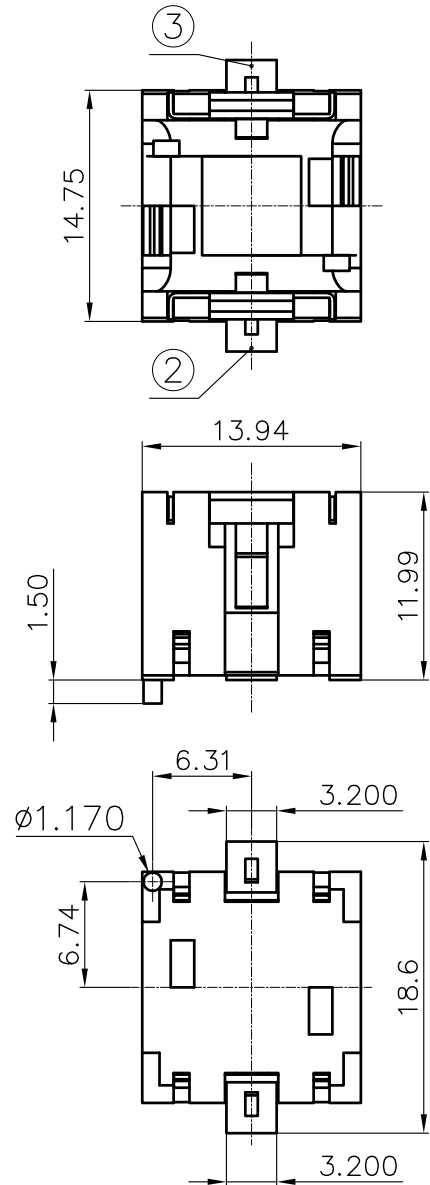


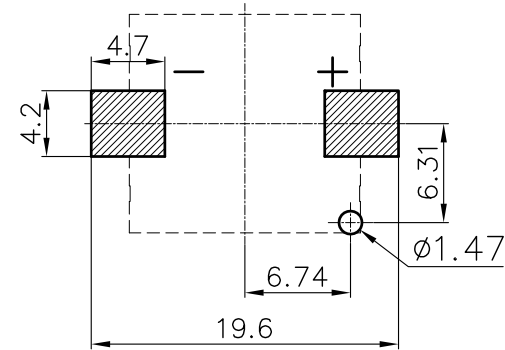
RoHS

5	6	7	8
ECN NO.	REV	DATE	DESCRIPTION



NOTE:

- 1.MATERIAL:
 - a.HOUSING:PPA
 - b.CONTACT:PHOSPHOR BRONZE (SURFACE PLATING: Au1u")
- 2.ELECTRIC:
 - a.CONTACT RESISTANCE: 30 MILLIOHMS MAX
 - b.INSULATION RESISTANCE: 1000 MEGA OHMS MIN
 - c.DIELECTNIC VOLTAGE: 500V AC ONE SEC LEVEL
 - d.OPERATING TEMPERATURE: -25° C~ +85° C



PCB Layout Diagram
Top View

NO.	PART NAME	Q'TY	MATERIAL	PLATING & COLOR
③	TERMINAL(-)	1	PHOSPHOR BRONZE, T=0.30mm	Gold Plating and Ni Under-Plating
②	TERMINAL(+)	1	PHOSPHOR BRONZE, T=0.30mm	Gold Plating and Ni Under-Plating
①	HOUSING	1	PPA	BLACK

UNLESS OTHERWISE SPECIFIED TOLERANCES				MeiYang Electronics Co.Ltd			
DECIMALS:	ANGLES:	DSND	LQ.HUANG	DATE	2018-07-14	TITLE:	
X : ±0.30	X : ±1°	CHKD		DATE		BS-2AG13-9 SMT	
X.X : ±0.25	X.X : ±0.5°	APVD	XY.XUE	DATE	2018-07-14	PART NO.:	
X.XX : ±0.20		WEIGHT:		SCALE:	SIZE:A4	VIEW:	BS-09-B2AA001
X.XXX : ±0.10		SHEET 1 OF 1		UNIT:mm	REV.:A/0	OBJECT:MY	DRAW NO.:MY-CP-0033